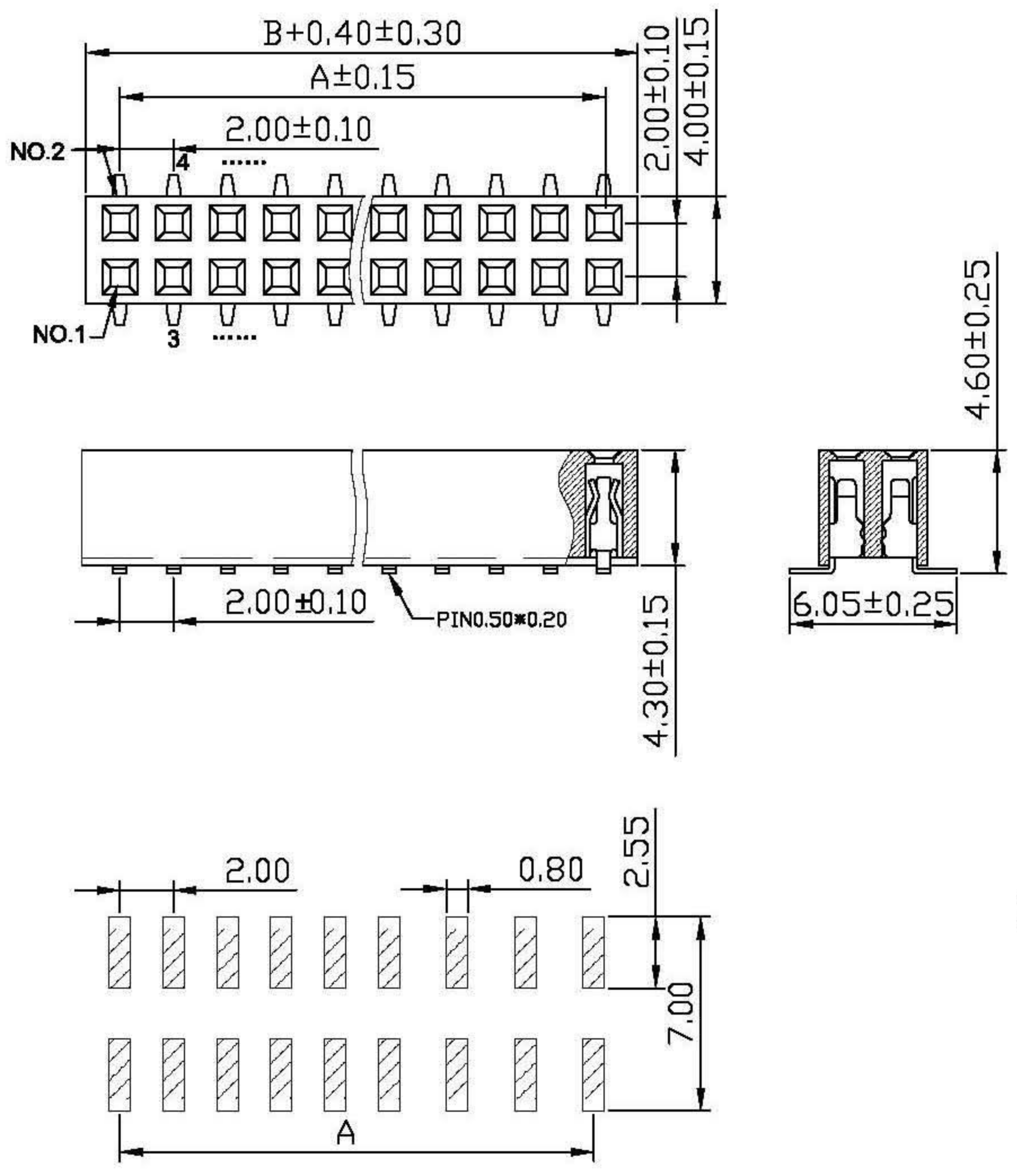


No. of Contacts	DIM A	DIM B
1	—	2.0
2	2.0	4.00
3	4.00	6.00
4	6.00	8.00
5	8.00	10.0
6	10.0	12.0
7	12.0	14.0
8	14.0	16.0
9	16.0	18.0
10	18.0	20.0
11	20.0	22.0
12	22.0	24.0
13	24.0	26.0
14	26.0	28.0
15	28.0	30.0
16	30.0	32.0
17	32.0	34.0
18	34.0	36.0
19	36.0	38.0
20	38.0	40.0
21	40.0	42.0
22	42.0	44.0
23	44.0	46.0
24	46.0	48.0
25	48.0	50.0
26	50.0	52.0
27	52.0	54.0
28	54.0	56.0
29	56.0	58.0
30	58.0	60.0
31	60.0	62.0
32	62.0	64.0
33	64.0	66.0
34	66.0	68.0
35	68.0	70.0
36	70.0	72.0
37	72.0	74.0
38	74.0	76.0
39	76.0	78.0
40	78.0	80.0



PCB LAYOUT

SPECIFICATIONS

Rated Current: 3.0AMP
 Contact Resistance: 20mΩ Max
 Withstand Voltage: 1000V AC/DC
 Insulation Resistance: 1000MΩ Min
 Operation Temperature: -40° c to +105° c

Contact Material: Brass
 Contact Plating: Au Over Ni
 Insulator Material: Polyester (UL94V-0)
 Standard: PA6T
 Max. Processing Temp: 230° C for 30-60 seconds
 (260° C for 10 seconds)

Ordering Information

2343 0 2 XX X B G1 M U N T 01

No. of Pins Per Row	Insulator Material Option	Post	Contact Plating	Post
1x40	A=BK-PBT	A=With inner post	G1: Gold Flash	A=Tray
1-40	B=BK-PA66	B=Without post	G2: 1.5U" Gold	T=Tube
	C=BK-PA6T	C=With external post	G3: 2U" Gold	R=Tape&Reel
	D=BK-PA46		G4: 3U" Gold	P=Membrane&Reel
	F=BK-LCP		G5: 5U" Gold	
			G6: 10U" Gold	
			G7: 15U" Gold	
			S0: Gold Flash/Tin	
			SN: Tin	

E				Units	mm	Scale	3:1	Drawing By	Date				
D				Tolerance Unless		Otherwise Specified		wang zhi gang					
C				.X ~ ±0.30				Check By	Date	Date	2014/02/11	Title	
B				.XX ~ ±0.25				zeng chun ming		Sheet	1 of 1	2.0PF 2XNP H=4.3 W=4.0 SMT U	
A				.XXX ~ ±0.20				Approval By	Date	Third Angle Projection		Drawing No.	
REV	ZONE	LTR	DESCRIPTION.	ECN.NO.	Date	Angle ~ ± 3°		zeng chun ming				234302XXXAG1MUNA01	REV
										File Path		Z/F:/ZLCPTD/2.0PF	A